SOLDER CONNECTION

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Technical Bulletin

TSC 920 Water Soluble VOC-Free Flux

DESCRIPTION

TSC 920 is a Water Soluble, VOC-Free flux specifically designed for industrial applications and inline solder tinning applications. This non-corrosive flux formulation may be used with any conventional tin/lead or lead-free solder alloys. TSC 920 flux contains propriety wetting agents within its formulation that increases its overall solderability performance at high temperatures. Post-soldering residues are non-corrosive and will not leave any black residues on the soldered substate.

FEATURES AND BENEFITS

- Excellent solderability at high temperatures
- Non-corrosive residues
- VOC-Free flux
- Suitable for all common leaded and lead free alloys.

APPLICATION METHODS

- Dipping
- Spraying or waving
- Dip-Tinning

TECHNICAL DATA

	Specification	Test Method	
Flux Classification	ORH1	JSTD-004-00B	
Color and Appearance	Clear Colourless Liquid		
Specific Gravity (g/cm3)	1.06 ± 0.01		
Solids Content	13 ± 1.0	IPC-TM-650 2.3.34	
pH Value (5% Soln)	2.0 ± 0.5	IPC-TM-650 2.3.13	
Chlorides & Bromides	6.0 ± 0.2		

CLEANING

Flux residues are water-based, therefore, no neutralizer or saponifiers are required to wash off the residues. Tap or deionized water may be used for cleaning. For optimum cleaning results, water temperature should be 40 - 60 °C (104 - 140 °F).

STORAGE & SHELF LIFE

Store in a closed container at room temperature. Solder flux shelf life is 2 years from date of manufacture.

DISPOSAL

TSC 920 contains hazardous ingredients, therefore, the flux should be disposed of in accordance with all local, regional, national and international regulations.

AVAILABILITY

920 Water Soluble flux is available in:

1L containers 5L containers 10L containers

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